

INTERNATIONAL STANDARD



Thermal-links – Requirements and application guide

(<https://standards.iteh.ai>)
Document Preview

IEC 60691:2023

<https://standards.iteh.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023>



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2024 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

IEC Secretariat
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigendum or an amendment might have been published.

IEC publications search - webstore.iec.ch/advsearchform

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee, ...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and once a month by email.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: sales@iec.ch.

IEC Products & Services Portal - products.iec.ch

Discover our powerful search engine and read freely all the publications previews, graphical symbols and the glossary. With a subscription you will always have access to up to date content tailored to your needs.

Electropedia - www.electropedia.org

The world's leading online dictionary on electrotechnology, containing more than 22 500 terminological entries in English and French, with equivalent terms in 25 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

International
Standards
Document Preview
iteh.ai

IEC 60691:2023

<https://standards.iteh.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023>



IEC 60691

Edition 5.1 2024-10
CONSOLIDATED VERSION

INTERNATIONAL STANDARD



Thermal-links – Requirements and application guide

(<https://standards.iteh.ai>)
Document Preview

IEC 60691:2023

<https://standards.iteh.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023>

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 29.120.50

ISBN 978-2-8322-9972-2

Warning! Make sure that you obtained this publication from an authorized distributor.

CONTENTS

FOREWORD.....	5
INTRODUCTION.....	7
1 Scope.....	8
2 Normative references	8
3 Terms and definitions	9
4 General requirements	11
5 General notes on tests	12
6 Classification	14
6.1 Electrical conditions.....	14
6.2 Thermal conditions.....	14
6.3 Resistance to tracking.....	14
7 Marking	14
8 Documentation	15
9 Constructional requirements	16
9.1 General.....	16
9.2 Lead secureness tests	17
9.2.1 General	17
9.2.2 Tensile test.....	17
9.2.3 Thrust test.....	17
9.2.4 Bending/twist test.....	17
9.3 Contacts used for the current path	18
9.4 Accessible mounting brackets or metal parts	19
9.5 Insulating materials.....	19
9.6 Resistance to tracking.....	19
9.7 Creepage distances and clearances.....	19
9.8 Temperature and humidity cycle conditioning.....	20
9.9 Terminals and terminations	20
10 Electrical requirements	21
10.1 Dielectric strength.....	21
10.2 Insulation resistance	21
10.3 Interrupting current	22
10.3.1 General	22
10.3.2 Specific conditions.....	22
10.4 Transient overload current	23
10.5 Limited short-circuit test.....	24
10.5.1 General	24
10.5.2 Test method	24
10.5.3 Fuse size (rating).....	25
10.5.4 Compliance	25
11 Temperature tests	25
11.1 General.....	25
11.2 Holding temperature, T_h	26
11.3 Rated functioning temperature, T_f	26
11.4 Maximum temperature limit, T_m	26
11.5 Ageing	27

12	Resistance to rusting	27
13	Manufacturer's validation programme	28
	Annex A (normative) Application guide.....	29
	Annex B (normative) Alternative ageing test for thermal-links with T_h greater than 250 °C for use in electric irons	30
	Annex C (normative) Conductive heat ageing test.....	31
	C.1 Conductive heat ageing test.....	31
	C.2 Method	31
	C.2.1 General	31
	C.2.2 Typical test fixture assembly.....	31
	C.2.3 Temperature setting.....	31
	C.2.4 Temperature behaviour.....	31
	C.2.5 Temperature monitoring.....	32
	C.3 Ageing	32
	C.3.1 General	32
	C.3.2 Cooling operation	32
	C.3.3 Premature operation	32
	C.4 Results	33
	C.5 Dielectric strength test	33
	C.6 Test oven.....	33
	Annex D (informative) Extended holding temperature evaluation.....	35
	D.1 Extended holding temperature conditioning test.....	35
	D.2 Load current interrupt test.....	35
	Annex E (normative) Seal ageing test.....	37
	Annex F (normative) Identification requirements	39
	Annex G (normative) Indelibility of markings.....	40
	Annex H (normative) Requirements for thermal-link packaged assemblies.....	41
	Annex I (informative) Holding temperature	45
	Bibliography.....	46
	 Figure 1 – Bending/twist test.....	18
	Figure C.1 – Typical test fixture assembly.....	33
	Figure C.2 – Typical thermal-link test oven	34
	Figure D.1 – Typical terminal block support test fixture	36
	Figure E.1 – Conditioning time versus oven temperature for proposed temperature index	38
	Figure G.1 – Apparatus for testing durability of markings	40
	 Table 1 – Test schedule.....	13
	Table 2 – Strength of leads and terminal parts – Minimum required tensile and thrust test forces.....	18
	Table 3 – Creepage distances and clearances (absolute minimum values)	20
	Table 4 – Test voltages for dielectric strength.....	21
	Table 5 – Test current for interrupting test	22
	Table 6 – Limited short-circuit test capacity	24
	Table H.1 – Push and pull force	43

Table H.2 – Minimum nominal cross-sectional area of conductor	43
Table H.3 – Allowed values for the materials used in the thermal-link package	44

iTeh Standards
(<https://standards.itih.ai>)
Document Preview

[IEC 60691:2023](https://standards.itih.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023)

<https://standards.itih.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023>

INTERNATIONAL ELECTROTECHNICAL COMMISSION

THERMAL-LINKS – REQUIREMENTS AND APPLICATION GUIDE

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) IEC draws attention to the possibility that the implementation of this document may involve the use of (a) patent(s). IEC takes no position concerning the evidence, validity or applicability of any claimed patent rights in respect thereof. As of the date of publication of this document, IEC had not received notice of (a) patent(s), which may be required to implement this document. However, implementers are cautioned that this may not represent the latest information, which may be obtained from the patent database available at <https://patents.iec.ch> or www.iso.org/patents. IEC shall not be held responsible for identifying any or all such patent rights.

This consolidated version of the official IEC Standard and its amendment has been prepared for user convenience.

IEC 60691 edition 5.1 contains the fifth edition (2023-03) [documents 32C/604/FDIS and 32C/605/RVD] and its amendment 1 (2024-10) [documents 32C/645/FDIS and 32C/648/RVD].

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendment 1. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

IEC 60691 has been prepared by subcommittee 32C: Miniature fuses, of IEC technical committee 32: Fuses. It is an International Standard.

This fifth edition cancels and replaces the fourth edition published in 2015 and Amendment 1:2019. This edition constitutes a technical revision.

This fifth edition includes the following significant technical changes with respect to the previous edition:

- a) requirements for thermal-link packaged assemblies;
- b) renew the requirements and definitions for T_h -test;

The harmonization of the USA national standard, UL 1020, fifth edition (withdrawn 2003), and IEC 60691:1993, together with its Amendment 1:1995 and Amendment 2:2000 have served as a basis for the elaboration of this standard.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

The following differing practices of a less permanent nature exist in the country indicated below:

- Annex C is required to be declared in the USA;
- Annex E is required in the USA, if applicable;
- Annex F is required to be declared in the USA.

In this standard, the following type is used:

- *compliance statements: in italic type.*

The committee has decided that the contents of this document and its amendment will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn, or
- revised.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

Thermal-links, defined as non-resettable devices functioning once only without refunctioning, are widely applied for the thermal protection of equipment in which, under fault (abnormal) conditions, one or more parts may reach hazardous temperatures.

As these devices have several aspects in common with miniature fuse-links and are used for obtaining a comparable degree of protection, this standard has endeavoured to lay down a number of basic requirements for such devices.

iTeh Standards
(<https://standards.iteh.ai>)
Document Preview

[IEC 60691:2023](https://standards.iteh.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023)

<https://standards.iteh.ai/catalog/standards/iec/c760e003-b24c-4dde-bed1-0ddcf64ee61e/iec-60691-2023>

THERMAL-LINKS – REQUIREMENTS AND APPLICATION GUIDE

1 Scope

This International Standard is applicable to thermal-links intended for incorporation in electrical appliances, electronic equipment and component parts thereof, normally intended for use indoors, in order to protect them against excessive temperatures under abnormal conditions.

NOTE 1 The equipment is not designed to generate heat.

NOTE 2 The effectiveness of the protection against excessive temperatures logically depends upon the position and method of mounting of the thermal-link, as well as upon the current which it is carrying.

This document may be applicable to thermal-links for use under conditions other than indoors, provided that the climatic and other circumstances in the immediate surroundings of such thermal-links are comparable with those in this standard.

This document may be applicable to thermal-links in their simplest forms (e.g. melting strips or wires), provided that molten materials expelled during function cannot adversely interfere with the safe use of the equipment, especially in the case of hand-held or portable equipment, irrespective of its position.

Annex H of this document is applicable to thermal-link packaged assemblies where the thermal-link(s) has already been approved to this standard but packaged in a metallic or non-metallic housing and provided with terminals/wiring leads.

This document is applicable to thermal-links with a rated voltage not exceeding 690 V AC or DC and a rated current not exceeding 63 A.

The objectives of this document are:

- a) to establish uniform requirements for thermal-links,
- b) to define methods of test, and
- c) to provide useful information for the application of thermal-links in equipment.

This document is not applicable to thermal-links used under extreme conditions such as corrosive or explosive atmospheres.

This document is not applicable to thermal-links to be used in circuits on AC with a frequency lower than 45 Hz or higher than 62 Hz.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60065:2014, *Audio, video and similar electronic apparatus – Safety requirements*

IEC 60112:2020, *Method for the determination of the proof and the comparative tracking indices of solid insulating materials*

IEC 60127-2:2014, *Miniature fuses – Part 2: Cartridge fuse-links*

IEC 60216-5:2008, *Electrical insulating materials – Thermal endurance properties – Part 5: Determination of relative thermal endurance index (RTE) of an insulating material*

IEC 60664-1:2020, *Insulation coordination for equipment within low-voltage supply systems – Part 1: Principles, requirements and tests*

IEC 60695-2-12:2021, *Fire hazard testing – Part 2-12: Glowing/hot-wire based test methods – Glow-wire flammability index (GWFI) test method for materials*

IEC 60695-2-13:2021, *Fire hazard testing – Part 2-13: Glowing/hot-wire based test methods – Glow-wire ignition temperature (GWIT) test method for materials*

IEC 60695-10-2:2014, *Fire hazard testing – Part 10-2: Abnormal heat – Ball pressure test method*

IEC 60695-11-10:2013, *Fire hazard testing – Part 11-10: Test flames – 50 W horizontal and vertical flame test methods*

IEC 60730-1:2013, *Automatic electrical controls – Part 1: General requirements*

IEC 60730-1:2013/AMD1:2015

IEC 60730-1:2013/AMD2:2020

IEC 61210:2010, *Connecting devices – Flat quick-connect terminations for electrical copper conductors – Safety requirements*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

clearance

shortest distance in air between two conductive parts

3.2

creepage distance

shortest distance along the surface of insulating material between two conductive parts

3.3

holding temperature

T_h

maximum ambient temperature of the thermal-link at which it will not change its state of conductivity during a specified time at a specified rated current

3.4**homogeneous series**

series of thermal-links having the same external dimensions and common overall construction, deviating from each other only in such characteristics (including ratings) that, for a given test, the testing of one or a reduced number of particular thermal-links of that series shall be taken as representative for all the thermal-links of the series

3.5**interrupting current** I_b

value of the current that the thermal-link is capable of interrupting at rated voltage and under specified circuit conditions

3.6**maximum temperature limit** T_m

temperature of the thermal-link stated by the manufacturer, up to which the mechanical and electrical properties of the thermal-link, having changed its state of conductivity, will not be impaired for a given time

3.7**pilot duty**

rating assigned to a switching device that controls the coil of another electro-mechanical device such as a solenoid, relay or contactor

3.8**portable equipment**

equipment which is moved while in operation or which can easily be moved from one place to another while connected to the supply

3.9**rated current** I_r

current used to classify a thermal-link

3.10**rated functioning temperature** T_f

temperature of the thermal-link which causes it to change its state of conductivity with a detection current up to 10 mA as the only load

3.11**rated voltage** U_r

voltage used to classify a thermal-link

3.12**thermal element**

metallic or non-metallic fusible material that is part of a thermal-link and is responsive to temperature by a change of state such as from solid to liquid at the temperature for which it is calibrated

3.13**thermal-link**

non-resettable device incorporating a thermal element, which will open a circuit once only when exposed for a sufficient length of time to a temperature in excess of that for which it has been designed

3.14 transient overload current

I_p

direct current pulse train which the thermal-link is able to withstand without impairing its characteristics

3.15 extended holding temperature

T_{h-100}

maximum temperature at which a thermal-link can be maintained while conducting the rated current at the rated voltage for a period of 100 weeks which will not cause the thermal-link to open circuit in accordance with extended holding temperature evaluation

Note 1 to entry: This is a rating for user consideration during the investigation of the end product.

Note 2 to entry: Annex D specifies the extended holding temperature evaluation.

3.16 conductive heat ageing test CHAT

test to evaluate a thermal-link for use in an appliance

Note 1 to entry: If it performs satisfactorily, the thermal-link will be assigned a CHAT rating. This rating is for end-product user consideration during the investigation of the end-use product.

Note 2 to entry: Annex C specifies the conductive heat ageing test.

4 General requirements

4.1 Adequate protection of the equipment against excessive temperatures not only depends upon the properties of the thermal-link but also to a large extent upon the mounting of the thermal-link in the equipment. Therefore the requirements of the application guide in Annex A shall be considered.

IEC 60691:2023

4.2 Thermal-links shall have adequate electrical and mechanical strength and shall be constructed so as to withstand all conditions of handling likely to be encountered during mounting and normal use, when used within the requirements of this document.

4.3 When a thermal-link changes its state of conductivity, no arc or flame shall be maintained, nor material expelled, that might impair the surrounding area or otherwise create a risk of electric shock or fire. In addition, there shall be no emission of substances (e.g. gases, liquids, dust, mist, vapour) which could cause a hazard.

For thermal-links using melting strips or wires, care should be taken to prevent molten material from short-circuiting or bridging creepage distances and clearances in air, so as to reduce the risk of impairing the insulation system of the equipment.

After it has functioned, the thermal-link shall not be damaged when subjected to temperatures not exceeding T_m , in such a way that the safety of the equipment with regard to risk of electric shock hazard and electrical breakdown is impaired. The thermal-link shall not reclose after it has operated.

4.4 For requirements for thermal-link packaged assemblies, see Annex H.

5 General notes on tests

5.1 The test conditions are as follows.

5.1.1 Unless otherwise specified, only tests that are not required to be performed inside an environmental chamber and/or test oven shall be carried out under the following atmospheric conditions:

- temperature: 15 °C to 35 °C,
- relative humidity: 25 % to 75 %,
- air pressure: $8,6 \times 10^4$ Pa to $1,06 \times 10^5$ Pa.

The required atmospheric conditions during testing can be controlled when carrying out the tests and during the duration of the tests. The required atmospheric conditions do not have to be maintained in a test laboratory when tests are not performed.

5.1.2 Where the conditions given in 5.1.1 have a significant influence, they shall be kept substantially constant during the tests.

5.1.3 If the temperature limits given in 5.1.1 are too wide for certain tests, these shall be repeated, in case of doubt, at a temperature of (23 ± 1) °C.

5.2 In every test report, the ambient temperature shall be stated. If the standard conditions for relative humidity or pressure are not fulfilled during the tests, a note to this effect shall be added to the report.

5.3 If the result of a test is influenced, to an appreciable extent, by the position and method of mounting of the specimen, the most unfavourable condition shall be chosen for the relevant tests and recorded.

5.4 If a thermal-link has been specifically designed for use in a special type of equipment and cannot be tested separately, the tests of this standard shall be performed in that equipment or in the relevant part of it, or similar.

5.5 When testing a homogeneous series of thermal-links, all the tests shall be applied to thermal-links with the lowest and highest T_f . Thermal-links with intermediate rated functioning temperatures need only be subjected to tests according to 10.3, 11.3, 11.4 and 11.5.

5.6 The number of specimens is as follows.

5.6.1 The total number of specimens required is 48. Out of a total of 48 specimens, 15 are kept as spares in case some of the tests have to be repeated. Out of a total of 48 specimens, 33 are divided into 11 groups assigned by alphabetical letters from A to K. Each group consists of three specimens. Tests shall be performed in the order indicated in Table 1 but, if so required, tests may be repeated, for example the test on marking (see Clause 7). Additional specimens may be needed according to the requirement of Table 1.

For optional tests, additional specimens should be required as per the applicable annexes.

5.6.2 If, in any of the tests carried out in accordance with any relevant test clause, a failure is reported, the cause of the failure will be identified and corrective action taken. Based on the failure analysis report and the corrective action, as a minimum, the test sequence shall be repeated on twice the number of revised specimens, and no further failures are allowed.

If no corrective actions are necessary, the test should be repeated with double the same size and no further deviation is allowed.